

# Vertex Detector for the Super KEK B factory

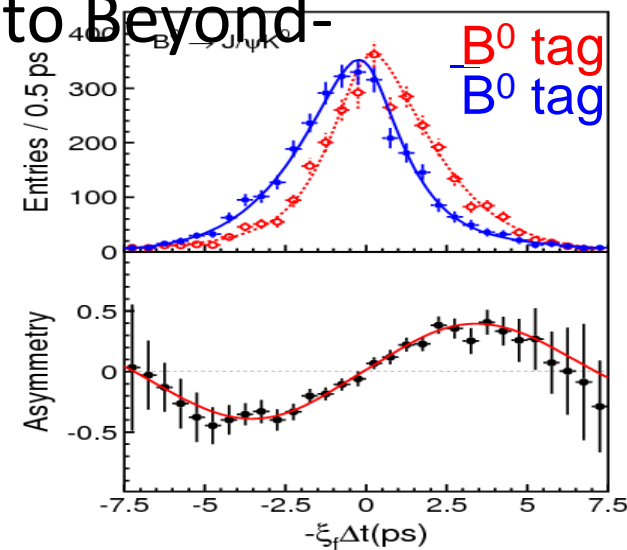
14 July 2016

T. Tsuboyama (KEK)

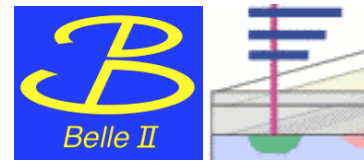
# Status of Super KEKB



- Super KEKB aims to explore the beyond-standard-model physics.
- KEKB & Babar established the standard model by observing the CP violation decays of  $B^0$  meson.
  - Luminosity  $\sim 2 \times 10^{34} / \text{cm}^2 / \text{sec}$
  - Integrated luminosity  $\sim 2 \text{ ab}^{-1}$  or 2 billion B-B events
- Super KEKB extends the physics reach to Beyond-standard-model physics
  - Luminosity  $\sim 80 \times 10^{34} / \text{cm}^2 / \text{sec}$
  - Integrated luminosity  $> 50 \text{ ab}^{-1}$ .

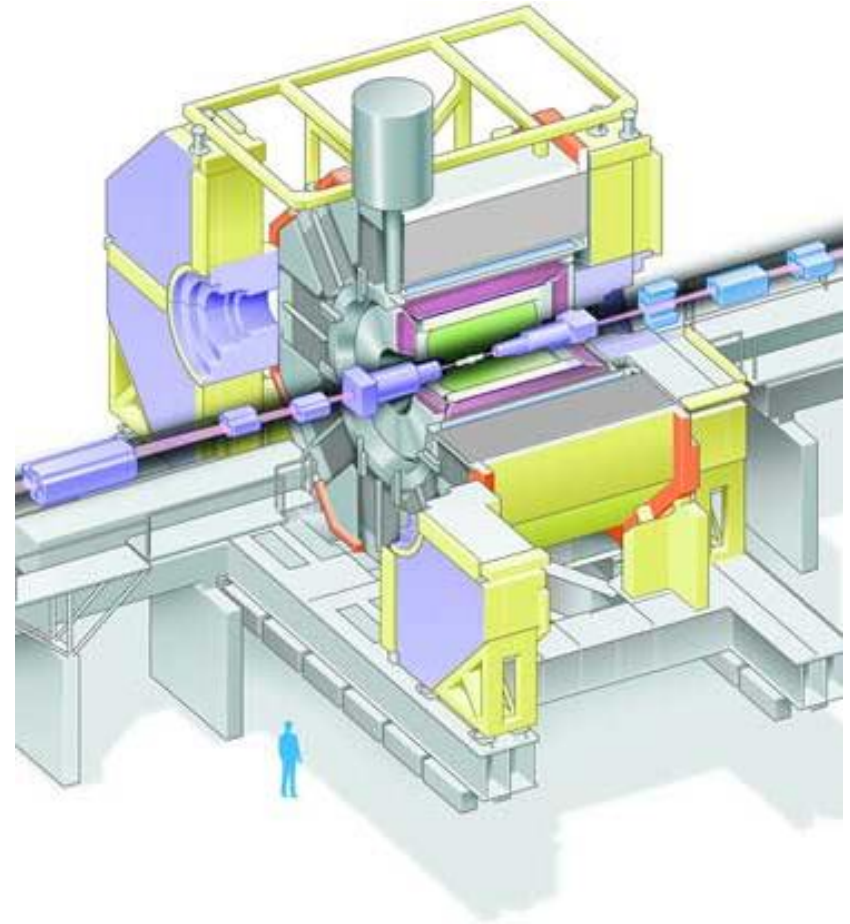
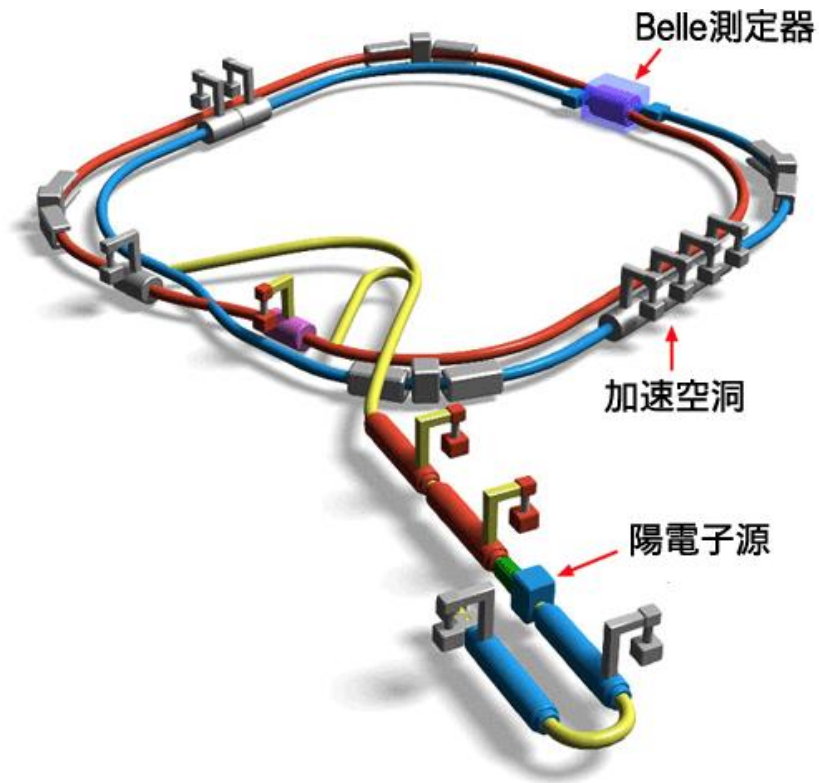


# KEKB Experiment

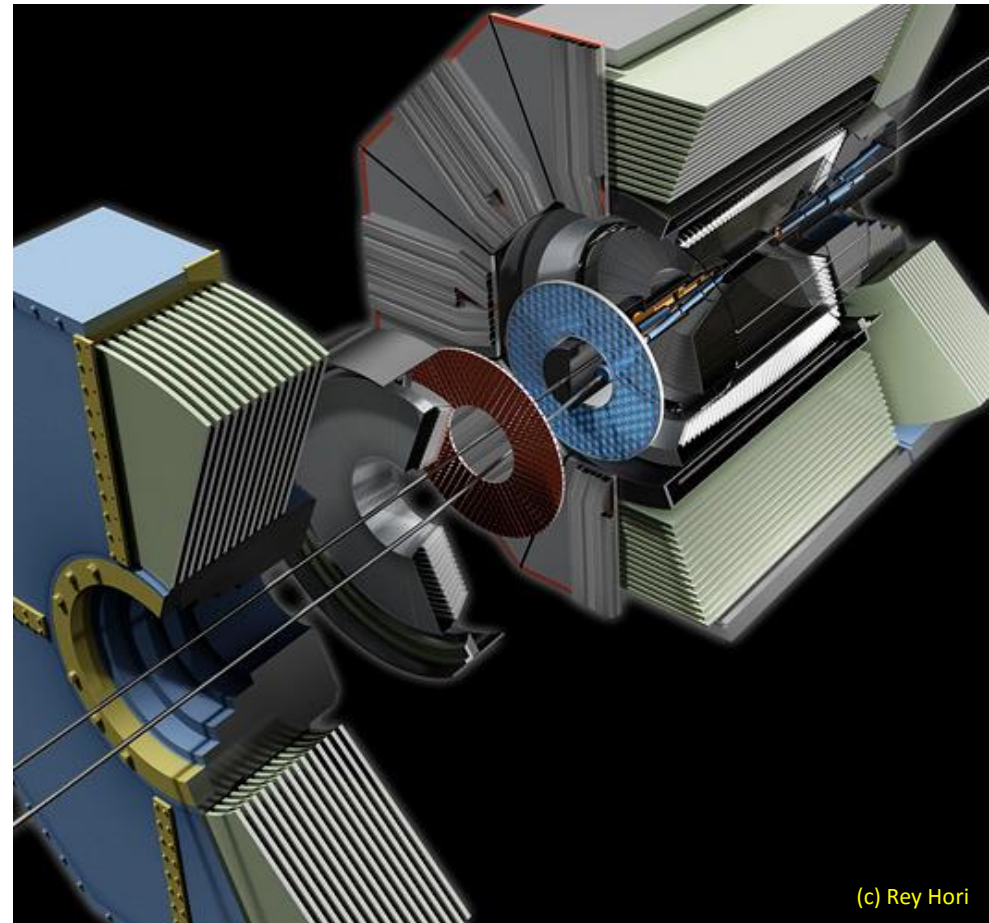
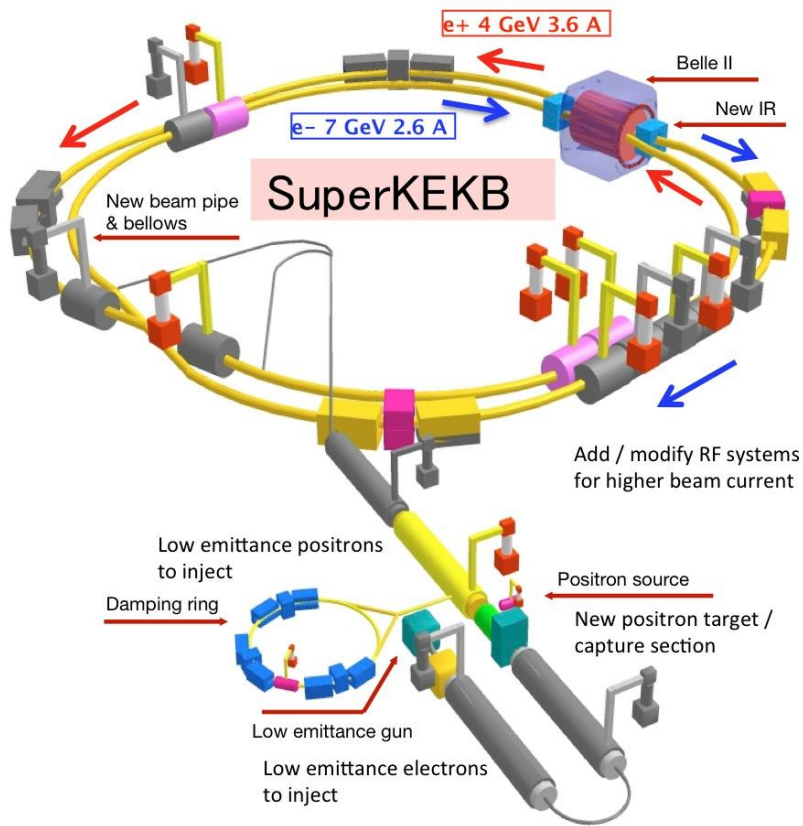


- KEBB Accelerator

- Belle



# Super KEKB



(c) Rey Hori

# Comparison of accelerator



	KEKB (achived)	Super KEKB (goal)
Accelerator	3km tunnel circumfarence, 508 MHz RF system	
Beam Energy	8 GeV e <sup>-</sup> 3.5 GeV e <sup>+</sup>	7 GeV e <sup>-</sup> 4 GeV e <sup>+</sup> (*)
Beam Current	1.2 A e <sup>-</sup> 1.6 A e <sup>+</sup>	2.6 A e <sup>-</sup> 3.6A e <sup>+</sup>
Luminosity	2x10 <sup>34</sup> /cm <sup>2</sup> /s (20/nb/sec)	8x10 <sup>35</sup> /cm <sup>2</sup> /s (0.8/fb/sec)
Beam size	1 μm x 150 μm	0.1 μm x 10 μm
Injection	Top up (trickle)	To up (trickle)
Collision rate	6 nsec (max)	4 nsec (max)

(\*) CM Energy can be adjusted up to Y(6S)

# Improvement of detector



- The physics target is same, the requirements to the detector do not change.
  - Detector size: Can not be larger/smaller
  - Full reconstruction capability
    - Thin material and large acceptance
    - Efficient high-resolution tracker and calorimeter
    - Particle Identification: Identify  $K^+/K^-$  from pions
  - Measurement of time evolution of B mesons
    - Precise and efficient Vertex measurement
- Requirements from to higher luminosity & backgrounds
  - Data acquisition rate 100 Hz  $\rightarrow$  5 kHz
  - Immunity to radiation effects
  - A higher detector segmentation
  - A better time resolution.

# Comparison of detectors



	<b>KEKB (achived)</b>	<b>Super KEKB (goal)</b>
Beam pipe	R=1.5cm	R=1.0 cm
Vertex detector	4layer silicon strip 2.5-10 cm	2layer pixel 1.8-2.3 cm 4layer Silicon strip 4 cm-16 cm
Central tracker	Small cell drift chamber 0.12-1 m	Small cell drift chamber 0.2-1.2 m
Particle ID Barrel	Aerogel Cerenkov counter (threshold)	TOP (ring image cerenkov counter projected to time information)
Endcap		Aerogel Rich counter
Calorimeter	Csl (TI) charge integration	Csi(TI) digital filtering
K-long/Muon	RPC in Iron yoke	Scintillator & RPC in Iron yoke
Magnetic Field	1.5 T (Super conducting Solenoidal magnet)	
DAQ	Max trigger rate 150 Hz	Trigger rate 5kHz
Computing	Managable in KEK	Worldwide with Grid and Cloud

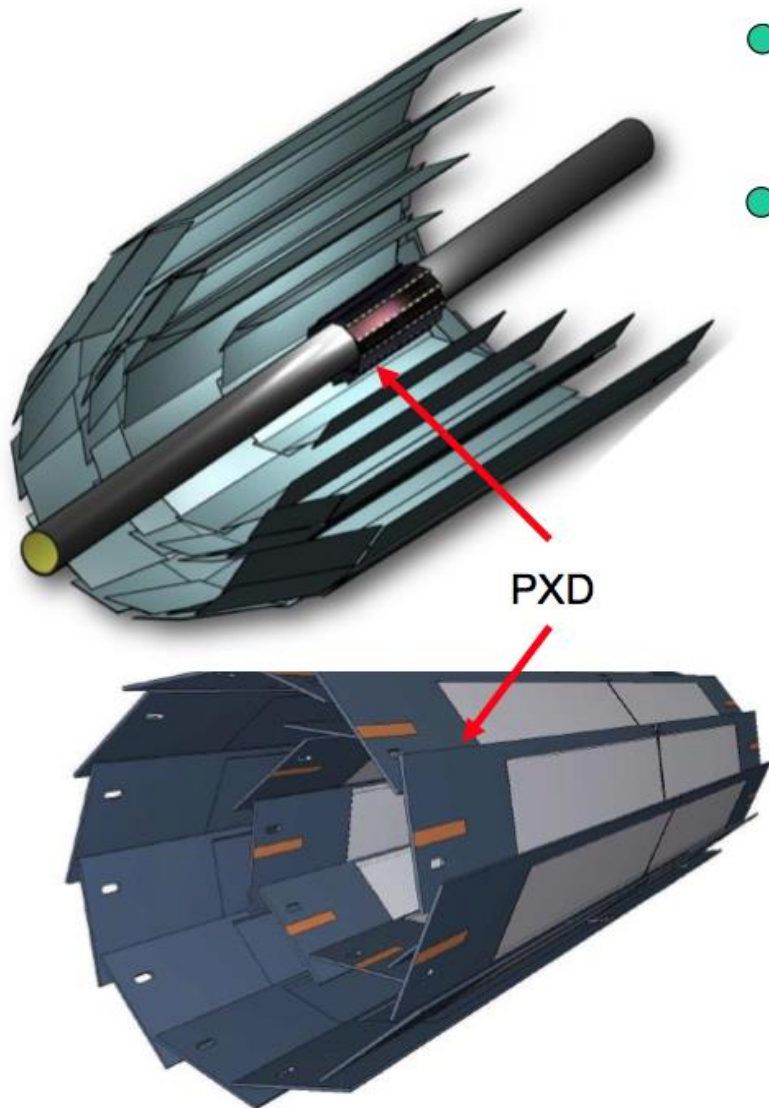
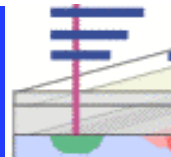
# Vertex detector



	<b>KEKB SVD (achieved)</b>	<b>Super KEKB (goal)</b>
Strip detector (SVD)	4-layer silicon strip 2.5-10 cm	4-layer Silicon strip 4 cm-16 cm
Sensor size	79mmx28	125mmx60mm
Total sensor area	0.6 m <sup>2</sup>	1.2 m <sup>2</sup>
Readout chip	VA1TA( Viking variant)	APV25 (developped for CMS)
Readout method (ganging)	1-3 sensors are read by one chip (ghost hits exist)	1 chip read out 1 sensor (no ghost hits)
Shaping time	800 nsec.	50 nsec
Pipeline	No	192 stage
Material thickness	0.4 % X <sub>0</sub> /layer: silicon 300 μm	0.6 % X <sub>0</sub> /layer: sensor+readout flex
Pixel detector (PXD)		2 layer DEPFET sensors R=1.4 2.2 cm
Thickness		0.1 % X <sub>0</sub> (silicon 75 μm)/layer 0.2 % X <sub>0</sub> /layer including peripherals
Readout		Rolling shutter (with injection veto)

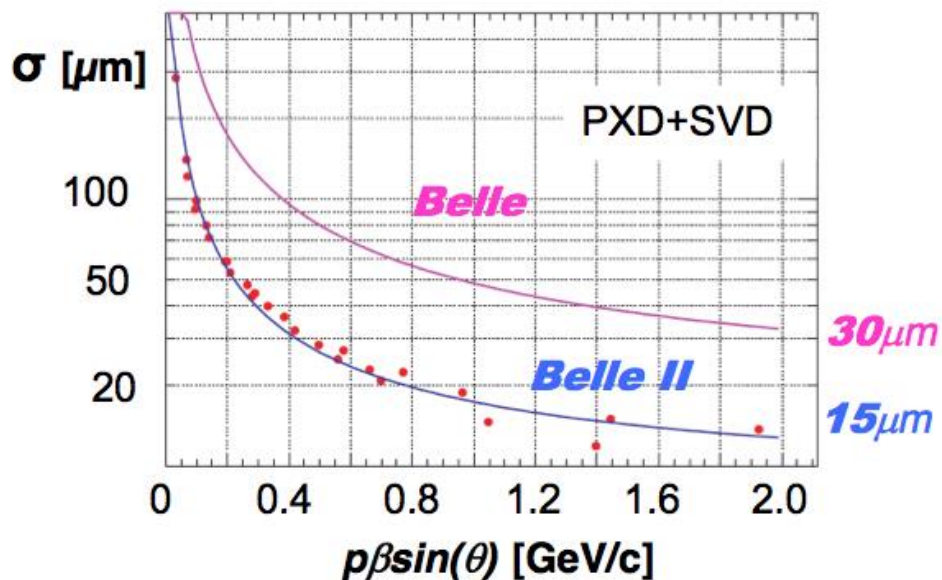


# Expected performance



- SVD: 4 layer Si strip detector (DSSD)  
( $R = 3.8, 8.0, 11.5, 14.0$  cm)
- PXD: 2 layer Si pixel detector (DEPFET technology)  
( $R = 1.4, 2.2$  cm)  
monolithic sensor  
thickness  $75 \mu\text{m}$  (!),  
pixel size  $50 \times 55 \mu\text{m}^2$  to  $50 \times 85 \mu\text{m}^2$  (depending on layer and  $z$ )

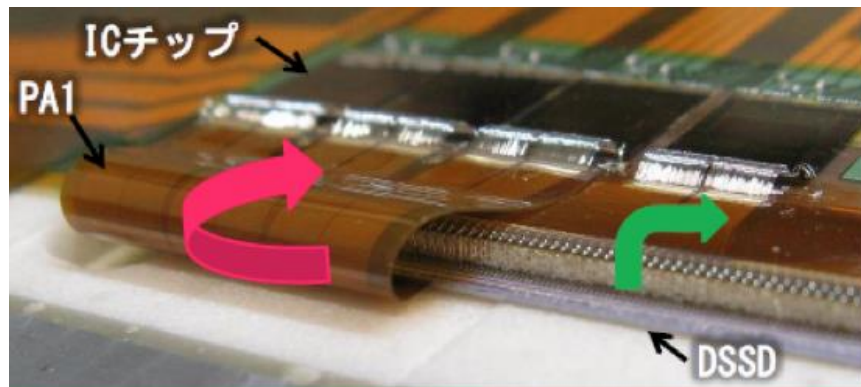
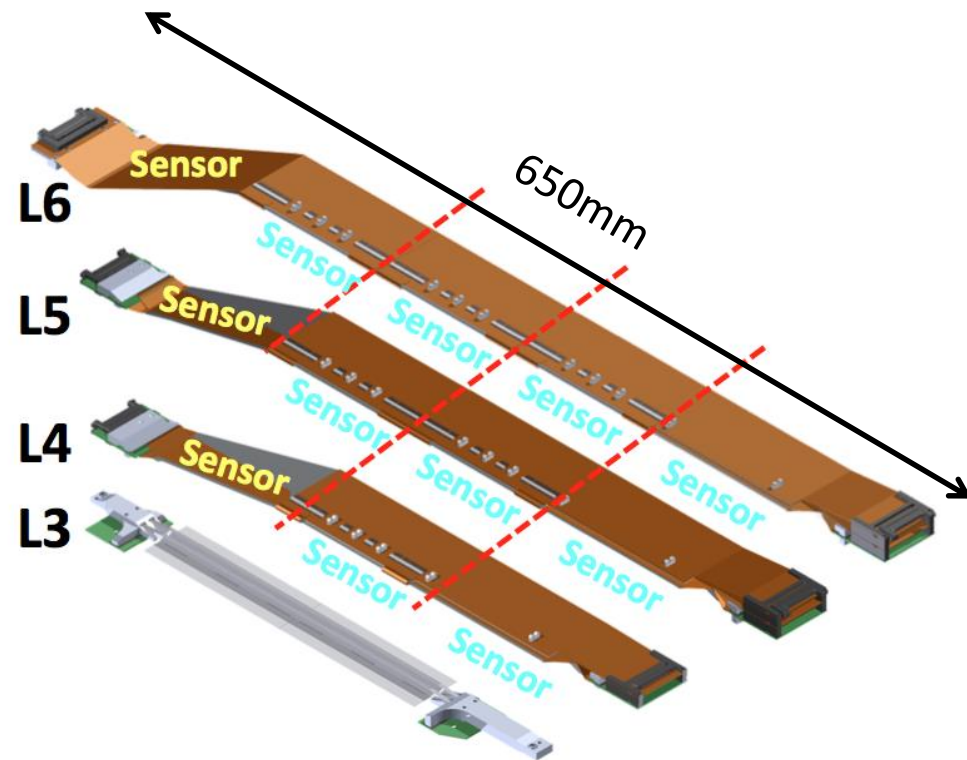
Significant improvement in  $z$ -vertex resolution



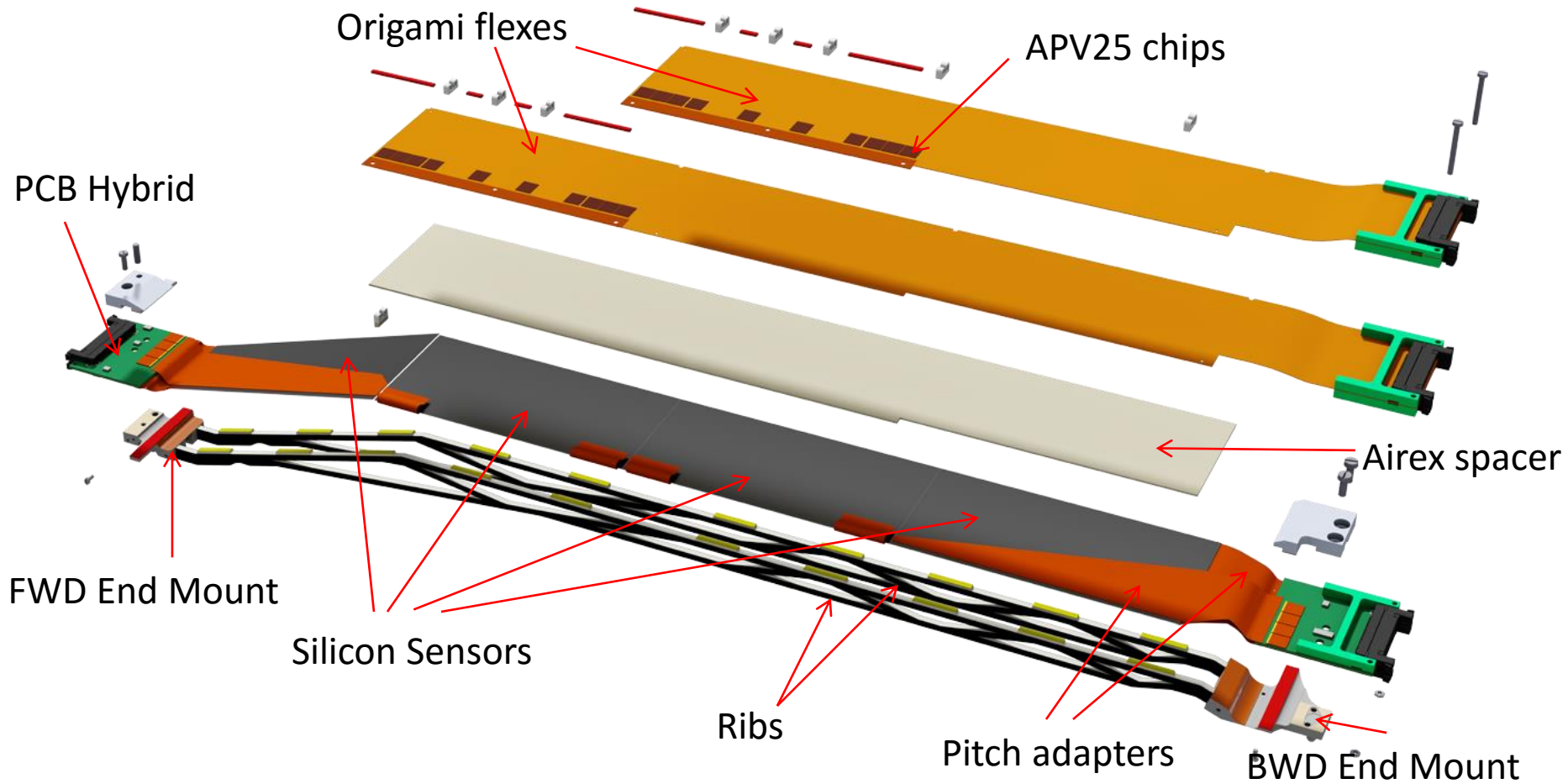
# SVD (Silicon Strip detector)



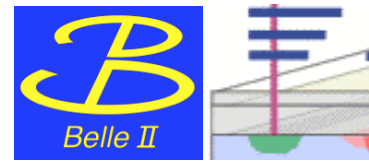
- 2-5 sensors are glued together to form "ladders"
- Forward region is covered with a slant sensor in order to reduce length and cost.
- Readout with APV25 developed for CMS
- APV25 is mounted on DSSD
- Data in the bottom side is brought to top side using flex circuits.



# Exploded view



# DEPFET pixel detector

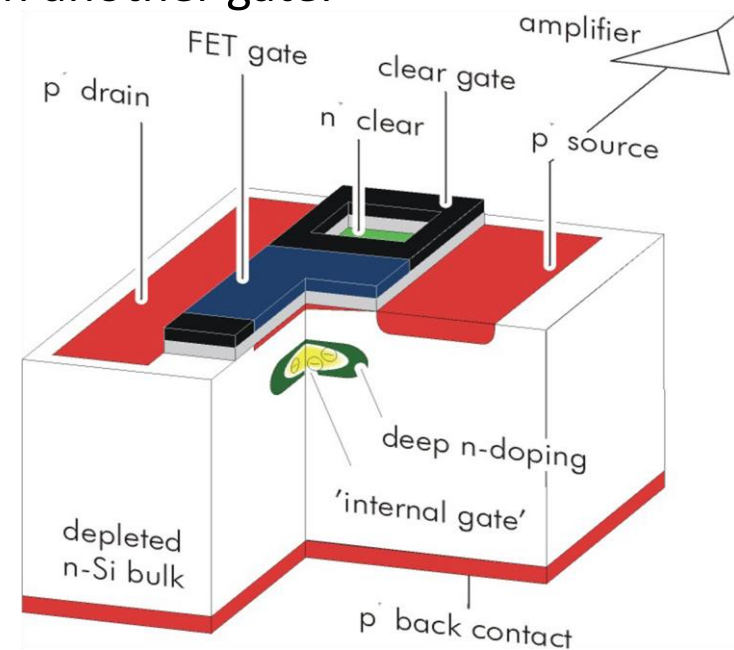
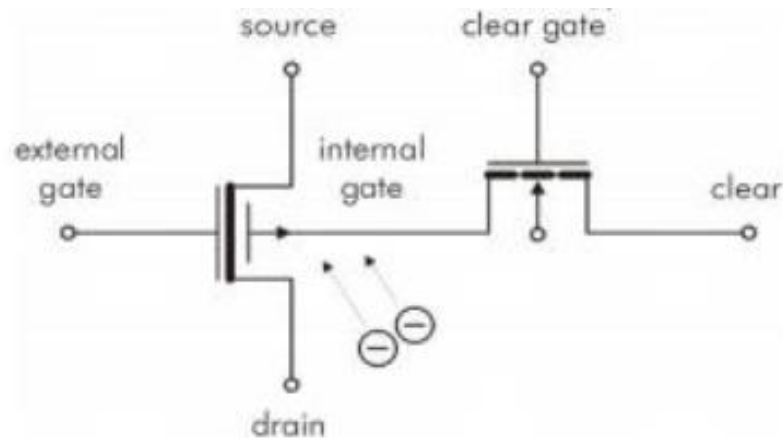


- DEPFET group joined to Belle group in 2009.
- The only available proved monolithic detector with fully depleted silicon sensors.
- Detector can be thinned to 50-75  $\mu\text{m}$ .
- Can be operated in room temperature.
- Max Planck institute fur Physik in Munich works with Siemens and they can only perform this special semiconductor process.

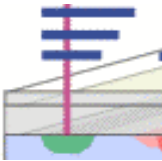
# DEPFET pixel detector



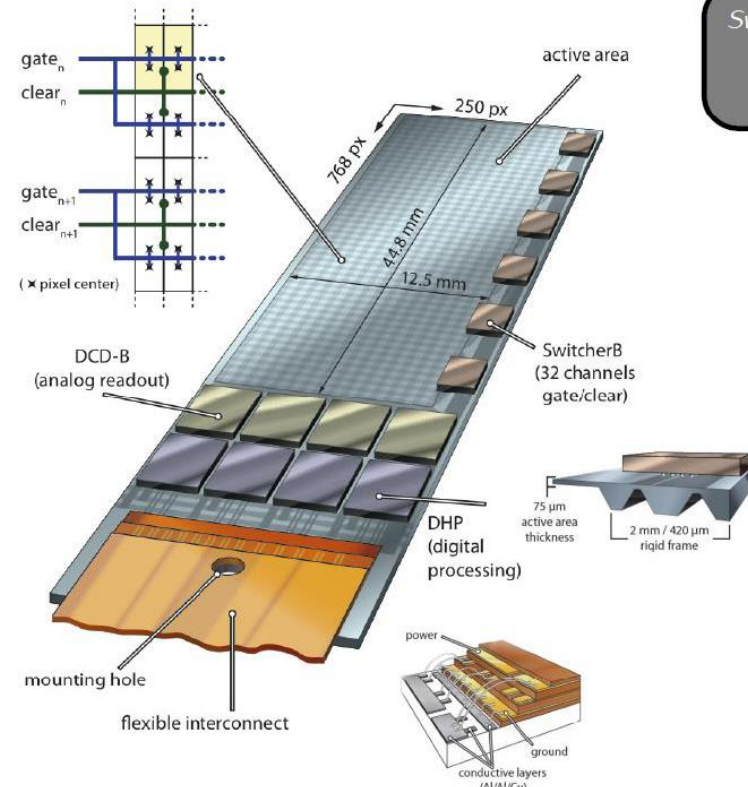
- DEPFET group joined to Belle group in 2009.
- The only available proved monolithic detector with fully depleted silicon sensors.
- Detector can be thinned to 50-75  $\mu\text{m}$ .
- MOSFET is produced at center of pixel.
- The charge induced in wafer is collected by the internal gate.
- The drain current is of MOSFET modulated by the potential of the internal gate.
- Pixels can be read out with scanning the source current and readout gate.
- The charge in the internal gate can be cleared with another gate.
- Rolling shutter readout.
- 20  $\mu\text{sec}$  frame rate for Super KEKB.



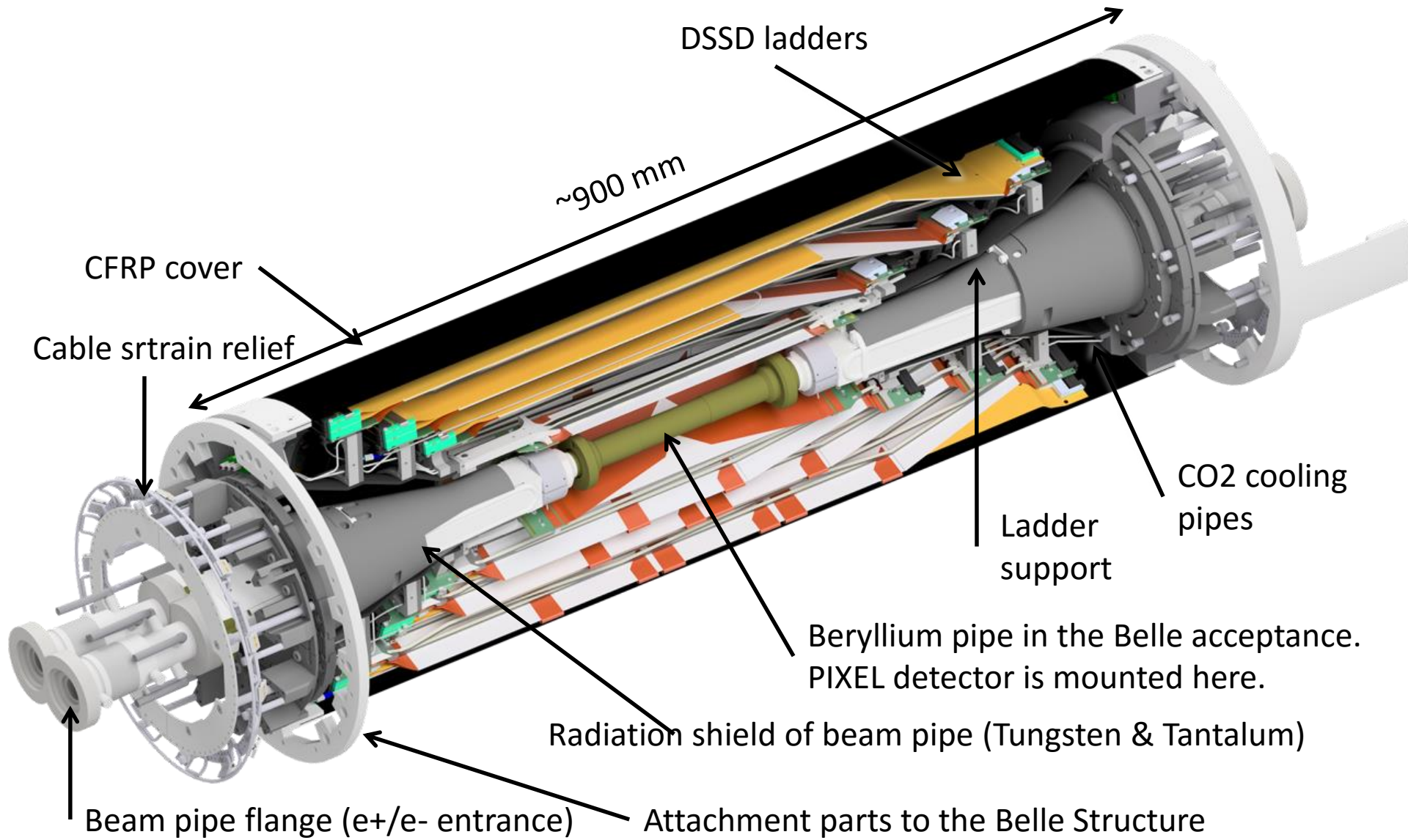
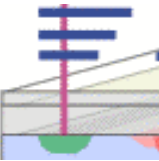
# Readout chain of DEPFET



- The drain current from pixels are digitized with DCD chips and "base line subtraction and hit pixel selection" is done on DHP chips on the same DEPFET wafer.
- The pixel scanning (and resetting) is mediated by switcher chips also on the DEPFET wafer.
- The output from DHP is sent to offline data acquisition system through the kapton flex circuit.
- Huge number of flip-chip bonding is also a challenge.



# SVD support mechanics



DSSD ladders

~900 mm

CFRP cover

Cable strain relief

CO2 cooling pipes

Ladder support

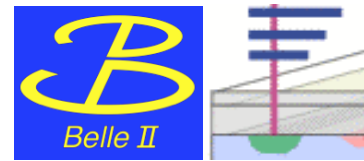
Beryllium pipe in the Belle acceptance. PIXEL detector is mounted here.

Radiation shield of beam pipe (Tungsten & Tantalum)

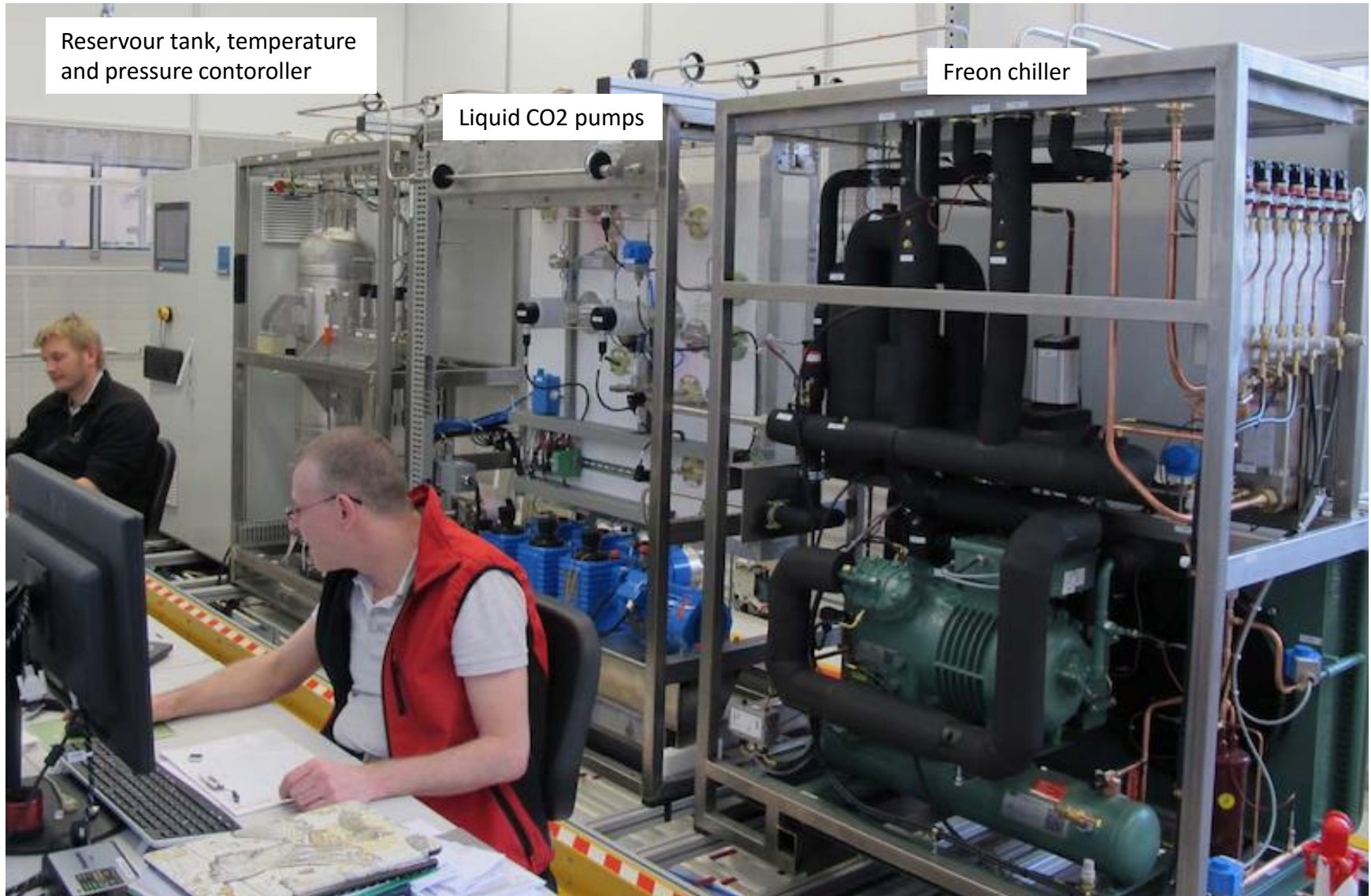
Beam pipe flange (e+/e- entrance)

Attachment parts to the Belle Structure

# The CO<sub>2</sub> cooling plant

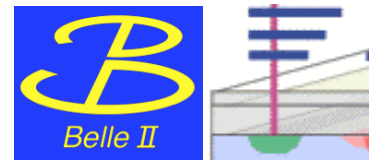


- IbBelle





# 2-phase CO<sub>2</sub> cooling



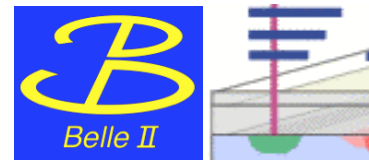
- CO<sub>2</sub> can be liquefied at  $T < 30^{\circ}\text{C}$  &  $P > 20$  MPa.
- Gas and liquid phases can co-exist conditions met.
- We chose 2MPa and  $-20^{\circ}\text{C}$  for SVD/PXD cooling
- If 1 g,  $-20^{\circ}\text{C}$  liquid CO<sub>2</sub> evaporates to gas, it absorbs 300 Joule.
- By evaporating 3g/sec, we can remove 1kW heat.
- Stainless steel pipes 0.1 mm wall thick and 1.5 mm inner diameter can hold 20 MPa pressure, in theory.
- Belle SVD/PXD adopted CO<sub>2</sub> cooling.
- The design of CO<sub>2</sub> plant for Atlas IBL pixel detector cooling is modified and construction finished this summer and shipped to KEK soon.

# Present status and Schedule



- 2016
  - Super KEKB completed the initial operation.
  - Beam current 1 A was stored to electron and positron rings (no collisions).
  - We are producing ladders (SVD) final sensors (DEPFET)
  - Mechanical discussions are near completion. Final mechanics production will be done.
- 2017:
  - SVD ladders will be mounted to the SVD support.
  - DEPFET detector will be prepared and tested in MPI Munich.
  - Super KEKB operation with Belle-2. Background and luminosity tuning starts.
- 2018
  - SVD and DEPFET will be combined and final commissioning is performed.
  - Super KEKB should achieve reasonable luminosity ( $> 2 \times 10^{34} / \text{cm}^2 / \text{s}$ ) and low beam background condition so VXD are not damaged.
  - Then, the vertex detector is installed and real physics operation will start.

# DEPFET collaboration



- Germany, Czech, Spain...

# SVD collaboration

- Japan, Australia, Austria, Czech, India, Italy, Korea, Poland
- I apologize if some country/institution is missing.